PB No	Paper ID	Title/Author(s)
1	**129**	**The Effect of Cu/SiO2 Rough Interface on TSV Electroplating Process for Electronic Packaging** Lv, Weishan; Lei, Xin; Liu, Jiaxin; Zhu, Fulong *Huazhong University of Science and Technology, China, People's Republic of*
2	**165**	**EM and system-level modelling of phased antenna arrays for D-band antenna-in-package and antenna-on-package** Svimonishvili, Tengiz; Rotaru, Mihai Dragos *Institute of Microelectronics (IME), Agency for Science, Technology and Research (A*STAR), Singapore*
3	**174**	**77GHz Wide-scan and High-gain three-port Grid Array Antenna (GAA) based on PCB** Zhao, Wei (1); Sun, Mei (2); Guo, Yongxin (1) *1: National University of Singapore, Singapore; 2: Institute of Microelectronics, A*STAR (Agency for Science, Technology and*
4	**175**	**Design of 900 MHz-band one-sided directional slot antenna by Bayesian optimization** Shinchi, Mao; Goodwill, Kumar; Kanaya, Haruichi *Kyushu University, Japan*
5	**177**	**Design of dual-band one-sided directional antenna for 5G communication** Shu, Yixuan; Kumar, Goodwill; Kanaya, Haruichi *Kyushu University, Japan*
6	**192**	**The effect of filler mass fraction on the physical properties of conductive silver adhesive** Yu, Ziniu; Lv, Weishan; Zhu, Fulong *School of Mechanical Science and Engineering, Huazhong University of Science and Technology, China, People's Republic of*
7	**201**	**Design of 900 MHz band metal-available compact dipole antenna for RFID system** Ito, Kenji; Kanaya, Haruichi *Kyushu University, Japan*
8	**203**	**Development of Wireless Energy Harvesting Circuit and Driving Experiment of Bluetooth System** Hosaka, Ryoma; Torigoe, Shota; Tagawa, Nobuya; Kanaya, Hruichi *Kyushu University, Japan*
9	**262**	**Simulation modeling of 600mm x 600mm fan-out panel level for warpage behavior based on chip first** Cheng, Kuo-ching; Chen, Bo-Heng; Chen, Cong-Wei; Chan, Ya-Fang; Wang, Burnet; Yang, Jeffrey; Fang, Jen-Kuang *Advanced Semiconductor Engineering, Taiwan*
10	**266**	**Development of Chip to Wafer Assembly with CuSnAg Microbump on Solder on Pad Interposer comparing Thermocompression versus Solder Reflow** Au, Keng Yuen; Chong, Ser Choong; Daniel, Ismael Cereno *Institute of Microelectronics, Singapore*
11	**285**	**Development of Flip-Chip Packaging for Monolithic Microwave Integrated Circuit** Wai, Leong Ching; Lim, Teck Guan; Chong, Ser Choong; Zhou, Lin *Institue of Microelectronics, Singapore*
12	**293**	**eWLB Fan-out Package for E-band Multi-Inputs/Outputs Phased Array IC** Zhai, Wenyao; Abdellatif, Ahmed Shehata; Pothula, Hari Krishna; Wessel, David *Huawei Technologies, Canada*
13	**296**	**Through Mold Vertical Interconnect Formation in FOWLP using Conductive Paste** Soh, Serine Siew Boon; Ho, David Soon Wee; Jaafar, Norhanani *Institute of Microelectronics, Singapore*
14	**342**	**Process and Integration Challenges for Via Last TSV (from top) on Functional LNA SOI wafers for 3D Heterogeneous chiplet integration** Wang, Xiangyu; Mihai, Dragos Rotaru; Yu, Haitao; Jong, Ming Chinq; Chai, Tai Chong; Chui, King Jien *Institute of microelectronics, Singapore*
15	357	**Thermally Annealed Tantalum filled Vertical Superconducting Interconnects for Scalable Quantum Computing Systems** Mishra, Harsh; bonam, satish; pandey, ullas; singh, shiv govind *IIT Hyderabad, India*
16	237	**Study of Cu Pad Expansion with Surrounded Dielectrics for Hybrid Bonding** Cheemalamarri, Hemanth Kumar; Ji, Lin; Lee, Wen; Vempati, Srinivasa Rao; Singh, Navab *Agency for Science and Technology Research (ASTAR) Singapore., Singapore*